PCN Number: 20181210000.0 Notification Date: Dec 13, 2018		
Title: Top-side symbol font change for Selected Device(s)		
Customer Contact: PCN Manager Dept: Quality Services		
Change Type:		
Assembly Site Design Wafer Bump Site		
☐ Assembly Process ☐ Data Sheet ☐ Wafer Bump Materia	al	
Assembly Materials Part number change Wafer Bump Process	S	
□ Packing/Shipping/Labeling □ Test Process □ Wafer Fab Materials		
Wafer Fab Process		
PCN Details		
Description of Change:		
Texas Instruments is pleased to announce a Top side symbol change for the affected device	es	
under the product affected section. Symbolization sample comparison are as follows:		
CURRENT PROPOSED		
YMLLLPG4 YMLLLLPG4		
LM9779CCVS LM9779CCVS		
(>B)		
Reason for Change:		
Marking simplification by removing the die run information which is already included on the Lot		
Trace Code information.		
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):		
None		
Anticipated impact on Material Declaration:		
$oxed{oxed}$ No Impact to the $oxed{oxed}$ Material Declarations or Product Content reports are drive	en	
Material Declaration from production data and will be available following the		
production release. Upon production release the revised		
reports can be obtained from the <u>TI Eco-Info website</u> . The	ere is	
no impact to the material meeting current regulatory		
compliance requirements with this PCN change.		
Changes to product identification resulting from this PCN:		
None		
Product Affected:		
DS90CR483AVJD/NOPB LM9740CCVS/NOPB LM9780CCVS/NOPB		
DS90CR483AVJDX/NOPB LM9779CCVS/NOPB		

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com